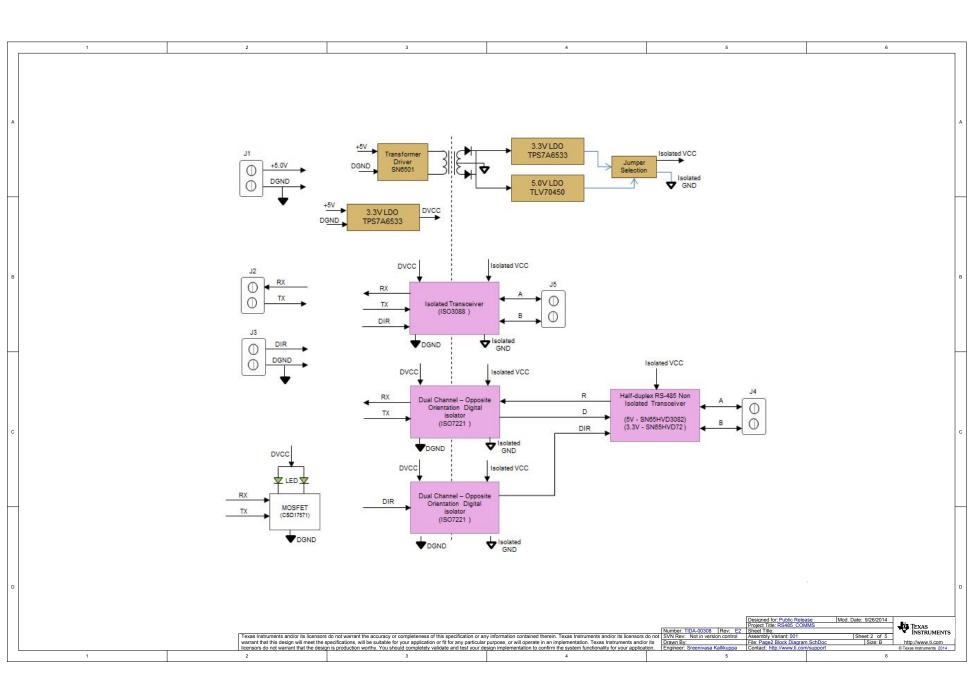
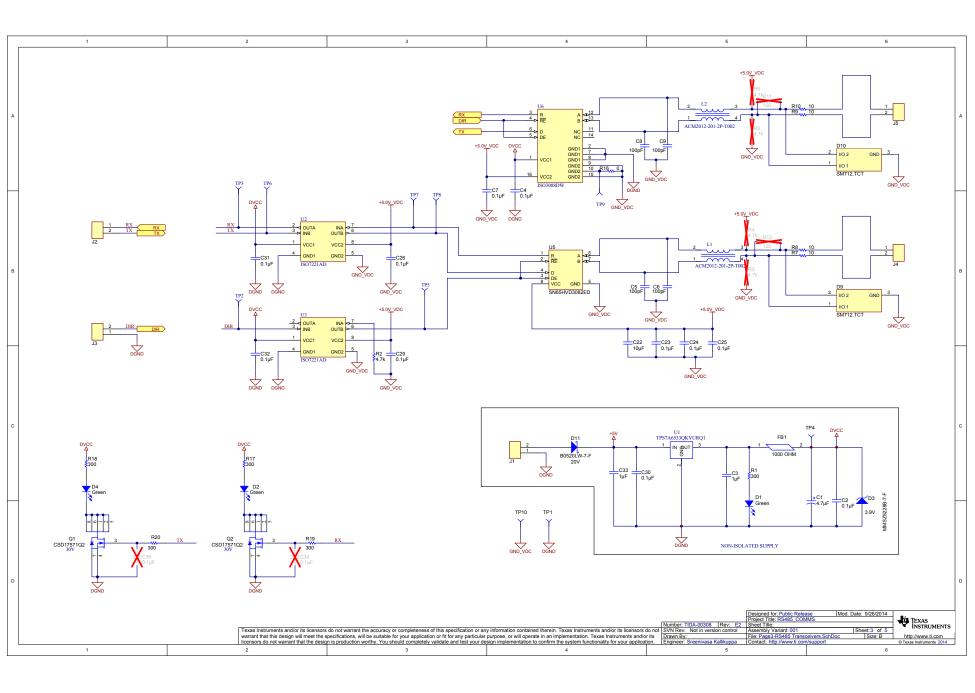
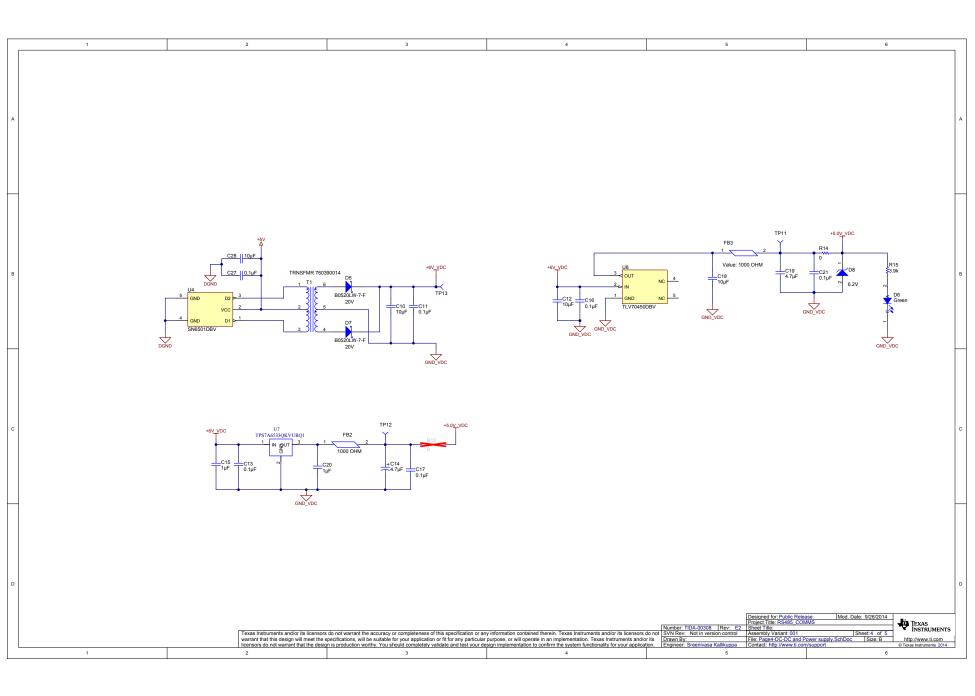
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A										A
		Page 2	Block Diagram							
	[Page 3	RS485 transceivers				Revision	Revision History		
в	[Page 4	DC-DC and Power Supp	ly						В
		Page 4	Hardware							
с										с
D										D
		1		Texas instruments and/or its licensor warrant that this design will meet the licensors do not warrant that the desi 2	s do not warrant the accuracy or completeness of this specification or a specifications, will be suitable for your application or if for any particula on its incluction worthy. You should completely validate and test your of 3	vy information contained therein. Texas instruments and/or its licensors of purpose, or will operate in an implementation. Texas instruments and/or sign implementation to confirm the system functionality for your applicant 4	Image: Number: TIDA-00308 Rev: E2 F No Drawn By: Not in version control A Ita: Drawn By: F F on. Engineer: Stender 5	Designed for: Public Release Mod. Date: roject Title: R5485_COMMS Sheet Title: Issembly Variant 001 [She ile: Pager Lines: Schloc Contact: http://www.il.com/support	9/26/2014 to 1 of 5 Size B http://www.ti.com 0 Texas instruments 2014 6	







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A						Label Table
						Variant Label Text
					-	001 ChangeMe! 002 ChangeMe!
					-	002 ChangeMe!
	FID2 FID3 FID1 FID6 FID	D4 FIDS			·	
					-	
					[
	PCB Number: TIDA-00308					
	PCB Rev: E2					
в						В
\vdash	PCB Label					H
	PCB Label Size: 0.65" x 0.20 *					
	272					
	ZZ2 Label Assembly Note This Assembly Note is for PCB labels only					
с	<u>ZZ4</u>					c
	ZZ4 Assembly Note These assemblies are ESD sensitive, ESD precaution:	ns shall be observed.				
		Ind all contaminants. Use of no clean flux is not acceptable.				
	ZZ1 Assembly Note	andards IPC-A-610 Class 2, unless otherwise specified.				
	These assemblies must comply with workmanship sta-	andards IPC-A-610 Class 2, unless otherwise specified.				
D						D
					Designed for: Public R Project Title: RS485 C	Velease Mod. Date: 9/26/2014 COMMS
		Texas Instruments and/or its licensor warrant that this design will meet the	s do not warrant the accuracy or completeness of this specification or an specifications, will be suitable for your application or fit for any particular an is production worthy. You should completely validate and test your de	y information contained therein. Texas Instruments and/or its licensors of purpose, or will operate in an implementation. Texas Instruments and/or	o not SVN Rev: Not in version control Assembly Variant: 001 rits Drawn By: File: Page5-Hardware	SchDoc Size: B http://www.ti.com
	1	licensors do not warrant that the desi	gn is production worthy. You should completely validate and test your de 3	sign implementation to confirm the system functionality for your applicat	on. Engineer: Sreenivasa Kallikuppa Contact: http://www.ti.	SchDoc Size: B http://www.ti.com com/support © Texas Instruments 2014
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